



ISO-9001-2008 Certified

## Selector Guide

### LOW THERMAL EXPANSION ADHESIVES

Epoxyset - Low Thermal Expansion adhesives are specifically designed to provide maximum adhesion while maintaining a balance of other important properties such as pot life, cure time & temperature, low thermal expansion, Glass transition temperature, dielectric properties etc.

These high performance adhesives are used for bonding and sealing critical high technology applications. They are recommended for bonding metals that will be subjected to thermal shock and temperature ranges from -65°C to 230°C. The fully cured products provide excellent dielectric properties, and very good thermal shock & impact resistance. They also have good resistance to weather, water, most petroleum products, mild acids & alkalis, and many other chemicals. **All adhesives meet NASA outgassing requirements.**

Product	Color	Mix Ratio by weight (R/H)	Pot life @ 25°C	Mix Viscosity @ 25°C (cPs)	Cure Schedule	Hardness (Shore)	Tg	CTE Below Tg (in/in/°C)	Lap Shear Strength @ 25°C	Thermal Conductivity (W/m <sup>2</sup> K)	Service Temp. Range	Volume Resistivity @ 25°C (Ohm-cm)	Shelf Life @ 25°C
EB-301	Beige	100/1	1 hr	Paste	24 hrs @ 25°C Or 2 hrs @ 100°C	D-91	80°C	32	2100	0.4	-65°C to 120°C	>10 <sup>15</sup>	1 Year
EB-347	Light Green	100/4.5	1 hr	45,000 – 55,000	24 hrs @ 25°C Or 2 hrs @ 100°C	D-92	84°C	25	2300	0.4	-65°C to 130°C	>10 <sup>15</sup>	1 Year
EB-347LV	Light Green	100/4.5	1-2 hrs	30,000-45,000	24 hrs @ 25°C Or 2 hrs @ 100°C	D-90	82°C	25	2300	0.4	-65°C to 130°C	>10 <sup>15</sup>	1 Year
EB-309	Green Tan	100/4.5	1-2 hrs	Paste	24 hrs @ 25°C Or 2 hrs @ 100°C	D-92	84°C	18	2300	0.5	-65°C to 130°C	>10 <sup>15</sup>	1 Year
EB-315	Beige	100/5.5	2 hrs	Paste	2 hrs @ 150°C Or 1 hr @ 165°C	D-92	175°C	25	2100	0.5	-65°C to 200°C	>10 <sup>15</sup>	1 Year
EB-348	Black	100/5	2 hrs	Paste	2 hrs @ 150°C Or 1 hr @ 165°C	D-93	194°C	23	2000	0.5	-65°C to 230°C	>10 <sup>15</sup>	1 Year

**DISCLAIMER:** All data given here is offered as a guide to the use of these materials and not as a guarantee of their performance. The user should evaluate their suitability for own purposes. Properties are typical and should not be used in preparing specifications. Statements are not to be construed as recommendations to infringe any patent.